

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | | | | | | | | | | | |
|--|------------------|---------------|------------------|------------------------|-------------|--------------------------|------------|-------------------|------------|-----------------------|------------|-------------------|------------|----------------|------------|------------------|------------|--------------|------------|---------------|------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | | | | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | | | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr><td>Yoichi OTSUKA</td><td>04/14/2009</td></tr> <tr><td>Yoshiyuki ENOMOTO</td><td>04/16/2009</td></tr> <tr><td>Kazunori NAGAHATA</td><td>04/16/2009</td></tr> <tr><td>Tadayuki KIMURA</td><td>04/20/2009</td></tr> <tr><td>Toshihiko HAYASHI</td><td>04/20/2009</td></tr> <tr><td>Kenichi AOYAGI</td><td>04/22/2009</td></tr> <tr><td>Kiyotaka TABUCHI</td><td>04/23/2009</td></tr> <tr><td>Iwao SUGIURA</td><td>04/24/2008</td></tr> <tr><td>Kensaku MAEDA</td><td>04/27/2009</td></tr> </tbody> </table> | | Name | Execution Date | Yoichi OTSUKA | 04/14/2009 | Yoshiyuki ENOMOTO | 04/16/2009 | Kazunori NAGAHATA | 04/16/2009 | Tadayuki KIMURA | 04/20/2009 | Toshihiko HAYASHI | 04/20/2009 | Kenichi AOYAGI | 04/22/2009 | Kiyotaka TABUCHI | 04/23/2009 | Iwao SUGIURA | 04/24/2008 | Kensaku MAEDA | 04/27/2009 |
| Name | Execution Date | | | | | | | | | | | | | | | | | | | | |
| Yoichi OTSUKA | 04/14/2009 | | | | | | | | | | | | | | | | | | | | |
| Yoshiyuki ENOMOTO | 04/16/2009 | | | | | | | | | | | | | | | | | | | | |
| Kazunori NAGAHATA | 04/16/2009 | | | | | | | | | | | | | | | | | | | | |
| Tadayuki KIMURA | 04/20/2009 | | | | | | | | | | | | | | | | | | | | |
| Toshihiko HAYASHI | 04/20/2009 | | | | | | | | | | | | | | | | | | | | |
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| RECEIVING PARTY DATA | | | | | | | | | | | | | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="width: 20%;">Name:</td><td>SONY CORPORATION</td></tr> <tr><td>Street Address:</td><td>1-7-1 Konan</td></tr> <tr><td>Internal Address:</td><td>Minato-ku</td></tr> <tr><td>City:</td><td>Tokyo</td></tr> <tr><td>State/Country:</td><td>JAPAN</td></tr> </table> | | Name: | SONY CORPORATION | Street Address: | 1-7-1 Konan | Internal Address: | Minato-ku | City: | Tokyo | State/Country: | JAPAN | | | | | | | | | | |
| Name: | SONY CORPORATION | | | | | | | | | | | | | | | | | | | | |
| Street Address: | 1-7-1 Konan | | | | | | | | | | | | | | | | | | | | |
| Internal Address: | Minato-ku | | | | | | | | | | | | | | | | | | | | |
| City: | Tokyo | | | | | | | | | | | | | | | | | | | | |
| State/Country: | JAPAN | | | | | | | | | | | | | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | | | | | | | | | | | |
| <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12434340</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 12434340 | | | | | | | | | | | | | | | | |
| Property Type | Number | | | | | | | | | | | | | | | | | | | | |
| Application Number: | 12434340 | | | | | | | | | | | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | | | | | | | | | | | |
| <p>Fax Number: (312)441-0570</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 312.277.2006</p> <p>Email: dayala@rdlklaw.com</p> <p>Correspondent Name: ROBERT J. DEPKE</p> <p>Address Line 1: ROCKEY, DEPKE & LYONS, LLC</p> <p>Address Line 2: SUITE 5450 SEARS TOWER</p> | | | | | | | | | | | | | | | | | | | | | |

CH \$40.00 12434340

500850247

PATENT
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Address Line 4: CHICAGO, ILLINOIS 60606-6306

ATTORNEY DOCKET NUMBER:

075834.01241

NAME OF SUBMITTER:

Robert J. Depke

Total Attachments: 3

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Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
SOLID-STATE IMAGING DEVICE, MANUFACTURING METHOD THEREOF, AND ELECTRONIC DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

| | |
|-------------------------------------|---|
| <u>Yoichi OTSUKA</u> | _____ |
| Name of first or sole inventor | Execution date of U.S. Patent Application |
| <u>Kanagawa, Japan</u> | _____ |
| Residence of first or sole inventor | |
| <u>Yoichi Otsuka</u> | <u>April 14, 2009</u> |
| Signature of first or sole inventor | Date of this assignment |

Yoshiyuki ENOMOTO

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Yoshiyuki Enomoto

Signature of second inventor

April 16, 2009

Date of this assignment

Kazunori NAGAHATA

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Kazunori Nagahata

Signature of third inventor

April 16, 2009

Date of this assignment

Tadayuki KIMURA

Name of fourth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Tadayuki Kimura

Signature of fourth inventor

April 20, 2009

Date of this assignment

Toshihiko HAYASHI

Name of fifth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fifth inventor

Toshihiko Hayashi

Signature of fifth inventor

April 20, 2009

Date of this assignment

KENICHI AOYAGIName of sixth inventorKANAGAWA, JAPANResidence of sixth inventorKenichi Aoyagi
Signature of sixth inventorExecution date of U.S. Patent ApplicationApril 22, 2009
Date of this assignmentKIYOTAKA TABUCHIName of seventh inventorKANAGAWA, JAPANResidence of seventh inventorKiyotaka Tabuchi
Signature of seventh inventorExecution date of U.S. Patent ApplicationApril 23, 2009
Date of this assignmentIWAO SUGIURAName of eighth inventorKANAGAWA, JAPANResidence of eighth inventorIwao Sugiura
Signature of eighth inventorExecution date of U.S. Patent ApplicationApril 24, 2009
Date of this assignmentKENSAKU MAEDAName of ninth inventorKANAGAWA, JAPANResidence of ninth inventorKensaku Maeda
Signature of ninth inventorExecution date of U.S. Patent ApplicationApril 27, 2009
Date of this assignment